

ABSTRACT OF THE DISCLOSURE

An in-line die attaching and curing apparatus for a multi-chip package (MCP) comprises at least one die attaching apparatus and at least one snap-cure apparatus. In one
5 embodiment, the die attaching apparatus comprises a loader, an index rail, a transfer gripper, a wafer loader, a chip alignment table, an adhesive applying device and an apparatus for placing a device on a chip mounting area. The die attaching apparatus further comprises a UV radiation device and a vision camera. The adhesive curing apparatus comprises a frame
10 providing unit being provided with the chip mounting frame from the index rail, a plurality of heating zones, each having a heating means, the heating means operable to raise and/or lower the temperature condition of the heating zones, a frame discharging unit discharging the chip mounting frame, and frame transfer means transferring the chip mounting frame from the frame providing unit to the frame discharging unit through the heating zones.